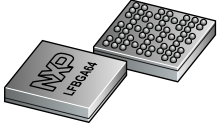


SOT1555-2

LFBGA64, plastic, low profile fine-pitch ball grid array; 64 bumps; 0.5 mm pitch; 5 mm x 5 mm x 1.11 mm body

23 August 2024

Package information



1 Package summary

Package type descriptive code	LFBGA64
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	02-05-2023
Manufacturer package code	98ASA02085D

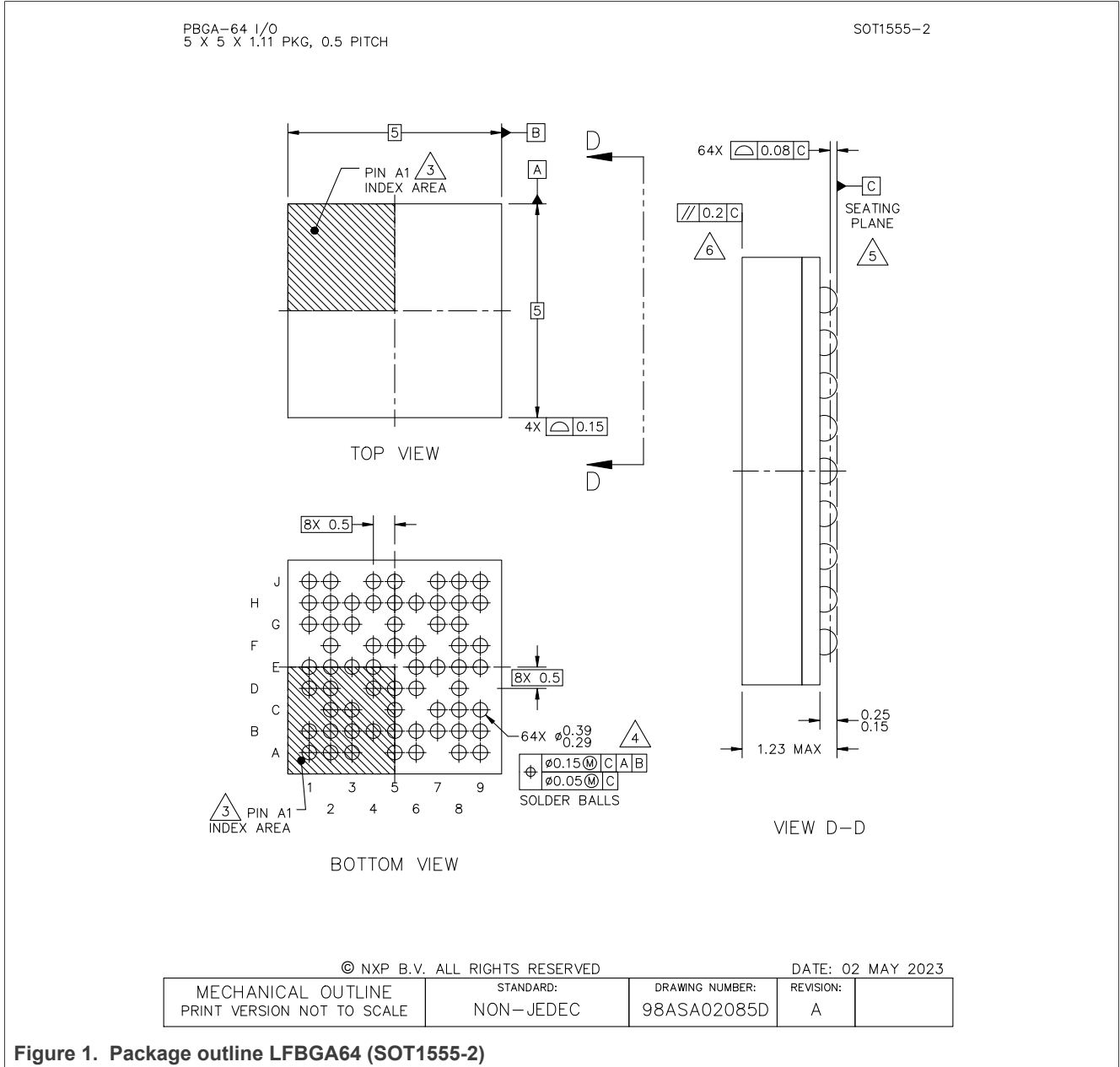
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.85	5	5.15	mm
package width	4.85	5	5.15	mm
package height	0.99	1.11	1.23	mm
package diameter	0.29	0.34	0.39	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	64	-	



LFBGA64, plastic, low profile fine-pitch ball grid array; 64 bumps; 0.5 mm pitch; 5 mm x 5 mm x 1.11 mm body

2 Package outline



LFBGA64, plastic, low profile fine-pitch ball grid array; 64 bumps; 0.5 mm pitch; 5 mm x 5 mm x 1.11 mm body

3 Soldering

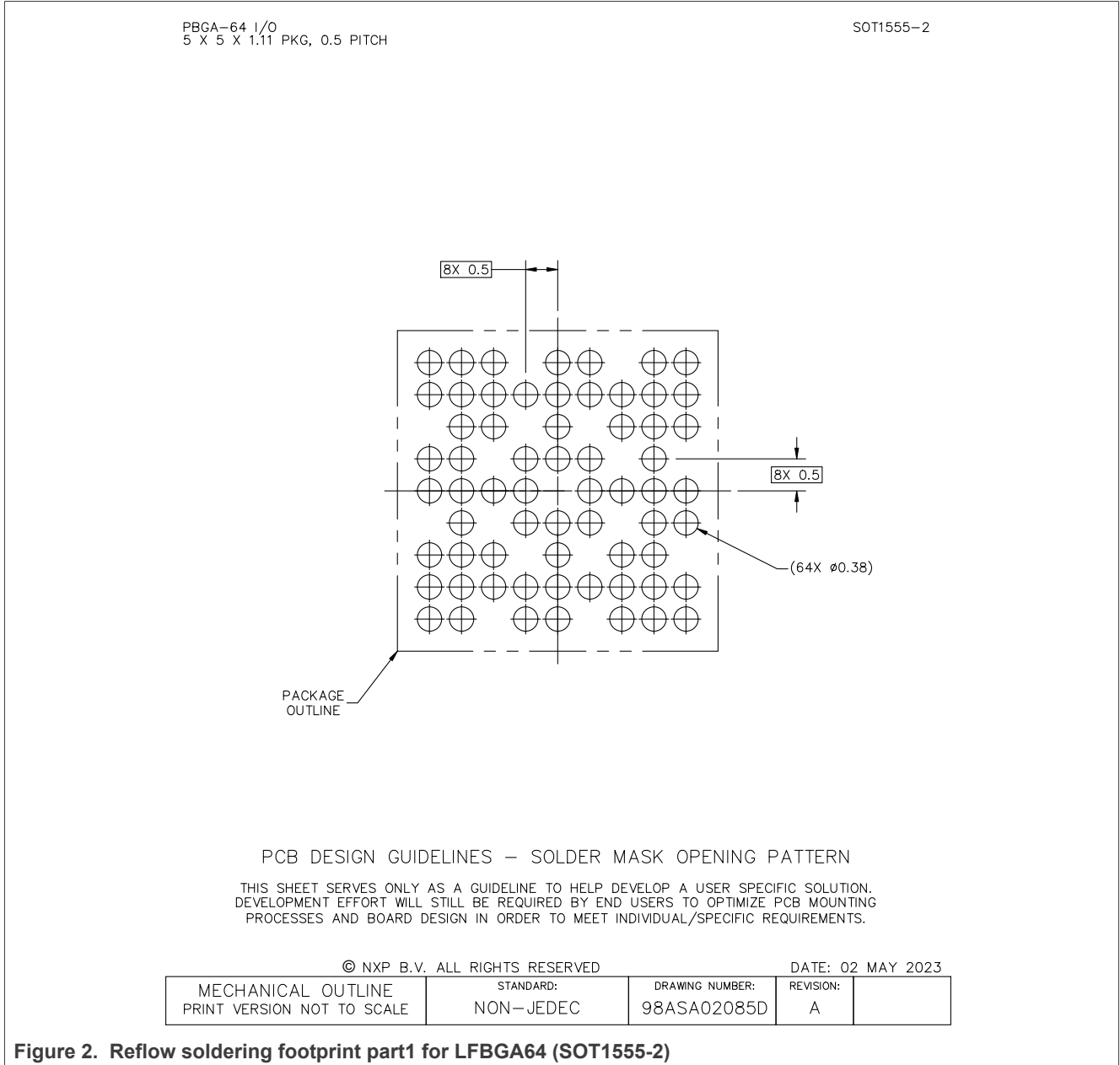
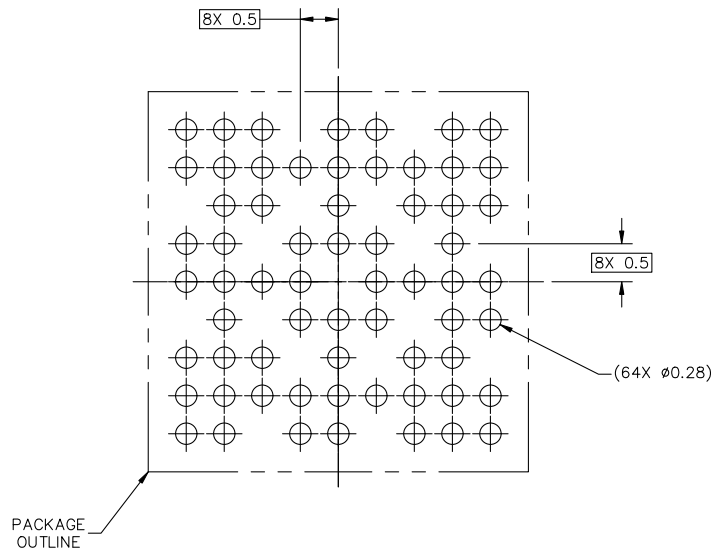


Figure 2. Reflow soldering footprint part1 for LFBGA64 (SOT1555-2)

LFBGA64, plastic, low profile fine-pitch ball grid array; 64 bumps; 0.5 mm pitch; 5 mm x 5 mm x 1.11 mm body

PBGA-64 I/O
5 X 5 X 1.11 PKG, 0.5 PITCH

SOT1555-2



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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DATE: 02 MAY 2023

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA02085D	REVISION: A	
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Figure 3. Reflow soldering footprint part2 for LFBGA64 (SOT1555-2)

LFBGA64, plastic, low profile fine-pitch ball grid array; 64 bumps; 0.5 mm pitch; 5 mm x 5 mm x 1.11 mm body

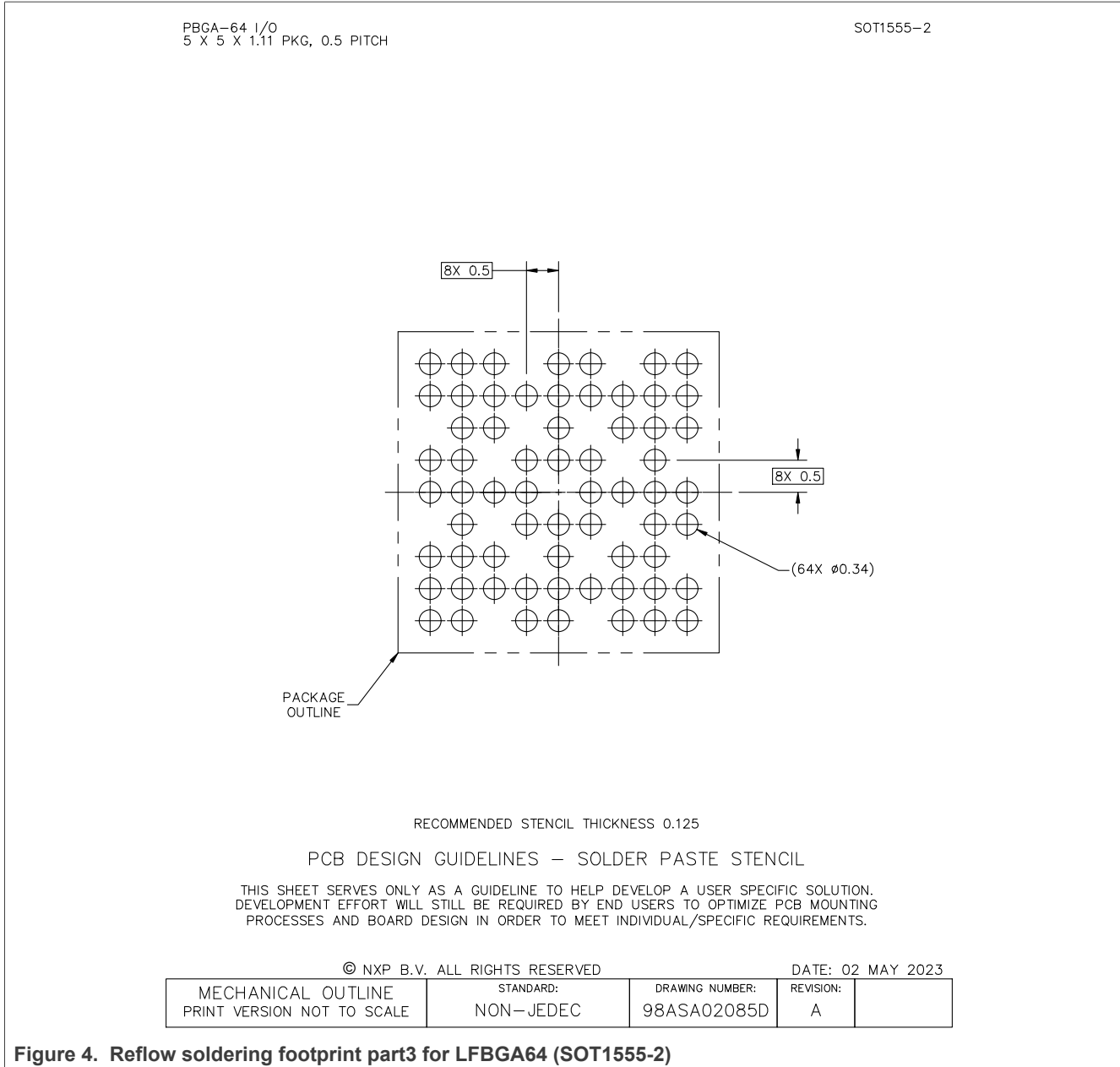


Figure 4. Reflow soldering footprint part3 for LFBGA64 (SOT1555-2)

LFBGA64, plastic, low profile fine-pitch ball grid array; 64 bumps; 0.5 mm pitch; 5 mm x 5 mm x 1.11 mm body

PBGA-64 I/O
5 X 5 X 1.11 PKG, 0.5 PITCH

SOT1555-2

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 02 MAY 2023

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Figure 5. Package outline note LFBGA64 (SOT1555-2)

4 Legal information

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LFBGA64, plastic, low profile fine-pitch ball grid array; 64 bumps; 0.5 mm pitch; 5 mm x 5 mm x 1.11 mm body

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